

# DIMM Validation Compliance Sheet

Must accompany all modules submitted for Web Validation

Please ensure that all cells are completely filled out

**Instructions :**

E-mail a copy of this form to the test lab prior to your shipment and attach hardcopy with shipment package.

**Sample Quantity required**

FBDIMM Validation	20
AMB Validation	16 R/C "A" & 16 R/C "B" (other R/C desired also)
FBDIMM Thermal Validation	10 (4 HS attached, 6 HS detached)
U-DIMM Validation	10
SoDIMM Validation	6

**Supplier Information**

Module Vendor	
Key Contact Name	
Key Contact Phone	
Key Contact e-mail	

**Module Information**

Module Type (FBDIMM, UDIMM, SoDIMM, etc..)	
Module Part Number	
Module Capacity / Size	
SPD revision (Programming should be verified)	
Speed / Frequency (MHz)	
Module Configuration (# of devices, # of Ranks)	
PCB supplier	

**SDRAM Information**

SDRAM Part Number	
SDRAM Supplier	
SDRAM Density (256Mb, 512Mb, 1Gb)	
SDRAM Width (x8, x4)	
SDRAM Package Type (uBGA, TSOP, etc)	
SDRAM Mask/Die Revision	
SDRAM Date Code	
SDRAM Speed	
SDRAM Core Timings CL- tRCD - tRP	
Does the device support RAS lockout?	
Device supports Concurrent Auto-Precharge?	
SDRAM Validated?	

**PCB Information**

Raw Card Type	
Gerber Revision	

Gerber JEDEC latest revision used? If no, reason for not using latest revision?	
<b>Validation Submission</b>	
Reason for validation (Evaluation, Resubmission, FBDIMM Validation, AMB Validation, Thermal Validation)	
If resubmission, why: (e.g. Fail Initial submission, Corrective action plan to XXX was used.)	

**Please, fill in below only if submitting FBDIMM type of samples.**

<b>AMB Information</b>	
AMB Vendor	
AMB Part Number	
AMB Revision	
AMB Date Code	
AMB Validated (Yes/No)?	

<b>Heat Spreader Information (FB-DIMM or AMB)</b>	
Heat Spreader Type (AHS, FDHS, etc)	
Heat Spreader Developer/Vendor	
Heat Spreader Part Number	
Heat Spreader Material	
Heat Spreader Revision	

#### **TIM (Thermal Insulation Material) Information**

	On AMB	On DRAM
Manufacturer		
Part number		
Type (grease, phase change, pad, etc.)		
Thickness (after assembly)		
Application method (cure, temperature, time, etc.)		

\*Heat Spreader Type:  
 AHS – AMB only Heat Spreader  
 FDHS – Full DIMM Heat Spreader

**NOTE: PMO Validation will check all SPD contents per JEDEC spec in validation. The following are for the SPD data quality verification purpose on top of the standard SPD check out.**

**Please complete the SPD Information below for Validation.**

**1. DRAM Idd Values for DT SPD Bytes 33 to 41:**

DRAM Idd Values from DRAM Data sheet	
IDD Name	IDD Value (mA)
IDD0	
IDD2N	
IDD2Q	
IDD2P	
IDD3N	
IDD4R	
IDD4W	
IDD5B	
IDD7	

**2. DRAM DT Byte Program Values (per JEDEC FBDIMM SPD Spec, Item #2003.05) updated to new spec number Rev 1.1**

SPD Byte (Dec)	Byte Description	SPD Value (Hex)
32	SDRAM Average Refresh Interval (tREFI)	
33	DRAM Tcasemax $\Delta$	
34	$\Psi$ T-A DRAM	
35	DT0/Tcase	
36	DT2N/DT2Q	
37	DT2P (Intel BIOS Unused)	
38	DT3N	
39	DT4R/4R4W	
40	DT5B	
41	DT7 (Intel BIOS Unused)	

**3. AMB DT Byte Program Values: (per JEDEC FBDIMM SPD spec, Item #2003.05)**

SPD Byte (Dec)	Byte Description	SPD Value (Hex)
87	Thermal Resistance of AMB Package	
88	AMB DT Idle_0	
89	AMB DT Idle_1	
90	AMB DT Idle_2	
91	AMB DT Active_1	
92	AMB DT Active_2	
93	AMB DT L0s	Intel BIOS Unused

#### 4. Thermal Byte Program Values: (New JEDEC Ballots / Intel requirements)

SPD Byte (Dec)	Byte Description	SPD Value (Hex)
94	R(AMB)	00 (Intel default)
95	R(AMB-DRAM)	00 (Intel default)
96	R(DRAM)	00 (Intel default)
97	R(DRAM-AMB)	00 (Intel default)
98	AMB T <sub>j</sub> max: [7:5]=Reserved; [4:0]=T <sub>j</sub> max	
99	FBD Category: [7:6]=Air Flow Impedance; [5:3]=DRAM type; [2:0]=HS type	